Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK3453

Switching Regulator Applications

• Low drain-source ON resistance: RDS (ON) = 0.72Ω (typ.)

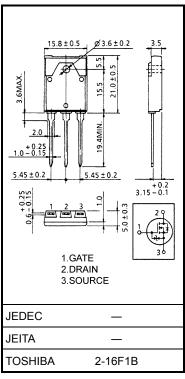
• High forward transfer admittance: $|Y_{fs}| = 7.0 \text{ S (typ.)}$

• Low leakage current: $IDSS = 100 \mu A (max) (VDS = 700 V)$

• Enhancement model: $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics			Symbol	Rating	Unit	
Drain-source voltage			V_{DSS}	700	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)			V_{DGR}	700	٧	
Gate-source voltage			V_{GSS}	±30	V	
Drain current	DC	(Note 1)	ID	10	Α	
	Pulse	(Note 1)	I _{DP}	30		
Drain power dissipation (Tc = 25°C)			P_{D}	80	W	
Single pulse avalanche energy (Note 2)			E _{AR}	420	mJ	
Avalanche current			I _{AR}	10	Α	
Repetitive avalanche energy (Note 3)			E _{AR}	8	mJ	
Channel temperature			T _{ch}	150	°C	
Storage temperature range			T _{stg}	-55~150	°C	



Weight: 5.8 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to case	R _{th (ch-c)}	1.56	°C/W	
Thermal resistance, channel to ambient	R _{th (ch-a)}	41.6	°C/W	

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 7.5 mH, $R_G = 25 \Omega$, $I_{AR} = 10 \text{ A}$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

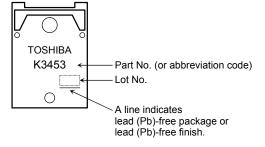
Electrical Characteristics (Ta = 25°C)

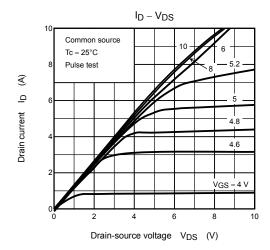
Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain-source bre	akdown voltage	V (BR) GSS	$I_G=\pm 10~\mu A,~V_{DS}=0~V$	±30	_	_	V
Drain cut-OFF cu	ırrent	I _{DSS}	$V_{DS} = 700 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	100	μА
Drain-source bre	Drain-source breakdown voltage		$I_D = 10$ mA, $V_{GS} = 0$ V	700	_		V
Gate threshold voltage		V _{th}	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$	2.0	_	4.0	V
Drain-source ON resistance		R _{DS (ON)}	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	_	0.72	1.0	Ω
Forward transfer admittance		Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 5 \text{ A}$	4.0	7.0		S
Input capacitance		C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	1700	_	pF
Reverse transfer capacitance		C _{rss}		_	40	_	
Output capacitance		Coss		_	200	_	
Switching time Fall	Rise time	t _r	$V_{GS}^{10 \text{ V}}$ $I_D = 5 \text{ A}$ V_{OUT}	_	40	_	- ns
	Turn-ON time	t _{on}		_	72	_	
	Fall time	t _f	$R_L = 40 \Omega$ $R_L = 40 \Omega$	_	42	_	
	Turn-OFF time	t _{off}		_	145	_	
Total gate charge (gate-source plus gate-drain)		Qg			53	_	nC
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	_	25	_	
Gate-drain ("miller") charge		Q _{gd}		_	28	_	

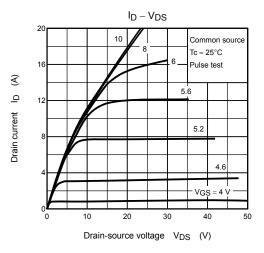
Source-Drain Ratings and Characteristics (Ta = 25°C)

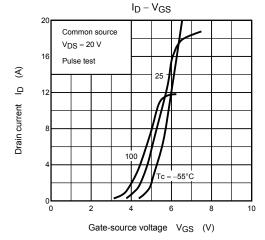
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	10	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	30	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 10 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V},$	_	1400	_	ns
Reverse recovery charge	Qrr	$dI_{DR}/dt = 100 \text{ A}/\mu\text{s}$		17.5	_	μС

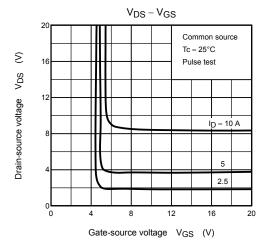
Marking

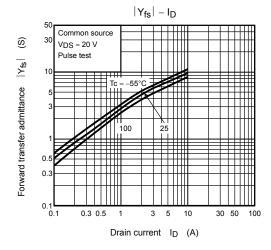


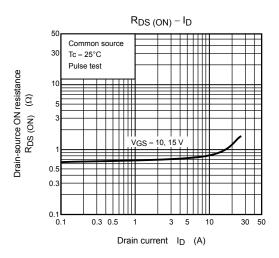


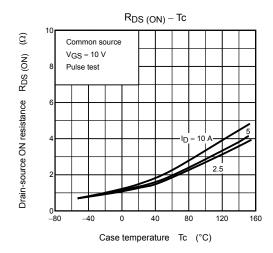


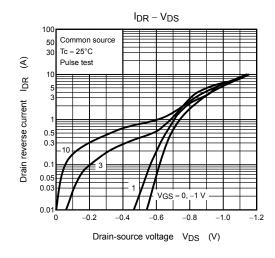


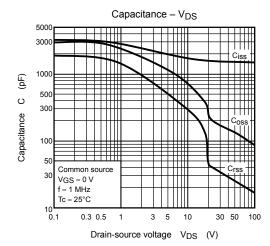


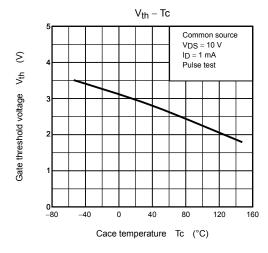


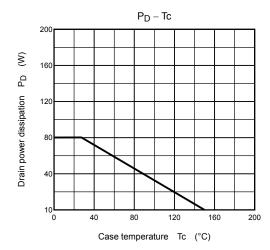


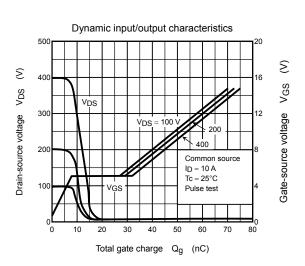


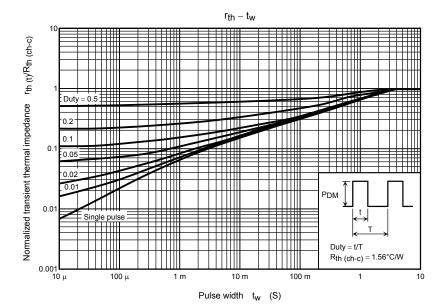


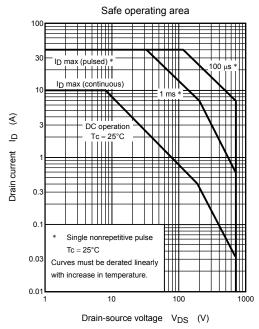


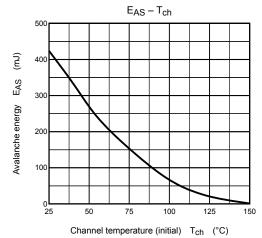


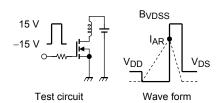












$$R_G = 25~\Omega$$

$$V_{DD} = 90~V,~L = 7.5~mH$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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